



## SSC8313GS1

### Dual P-Channel Enhancement Mode MOSFET

#### ➤ Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub> Typ.	I <sub>D</sub>
-12V	±8V	38mΩ@-4V5	-6A
		47mΩ@-2V5	
		61mΩ@-1V8	

#### ➤ Description

This device is produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device particularly suits low voltage applications such as portable equipment, power management and other battery powered circuits, and low in-line power dissipation are needed in a very small outline surface mount package. Excellent thermal and electrical capabilities.

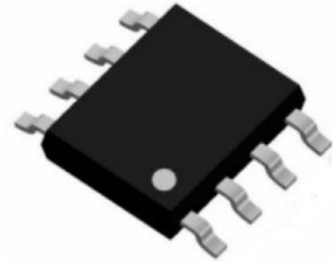
#### ➤ Applications

- NB Battery
- DC/DC Conversion
- Load Switch

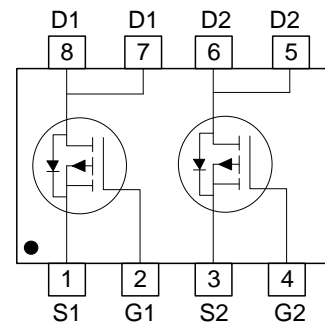
#### ➤ Ordering Information

Device	Package	Shipping
SSC8313GS1	SOP-8	4000/Reel

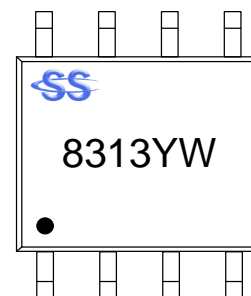
#### ➤ Pin configuration



**SOP-8**



**Pin Configuration (Top View)**



**Marking**

(YW: Internal Traceability Code)



➤ **Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	-12	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 8$	V
$I_D$	Continuous Drain Current <sup>a</sup>	-6	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	-20	A
$P_D$	Power Dissipation <sup>c</sup>	1.5	W
$T_J$	Operation junction temperature	-55~150	°C
$T_{STG}$	Storage temperature range	-55~150	

➤ **Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	60	°C/W
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	25	

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design. The power dissipation is based on the  $t \leq 10s$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

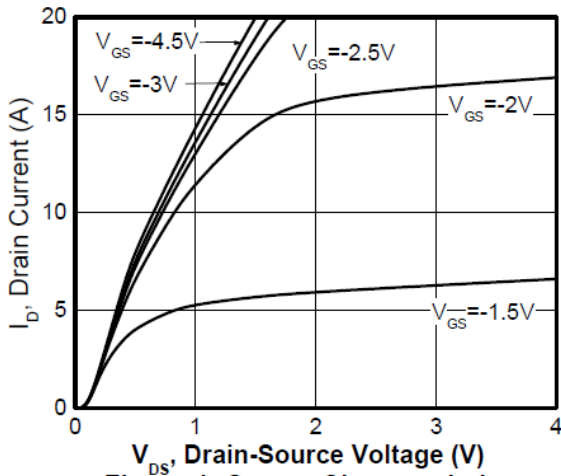


➤ **Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

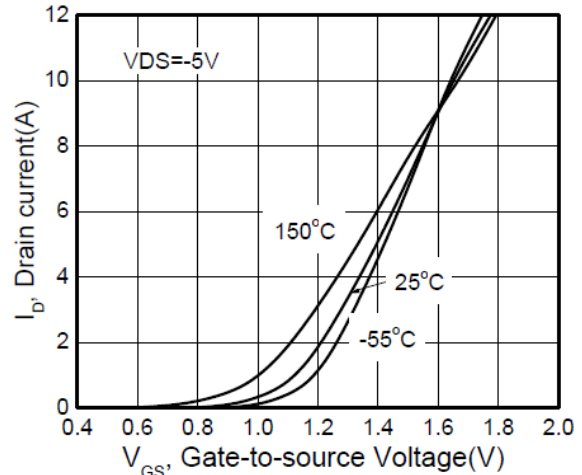
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-12			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250uA	-0.45	-0.62	-1.2	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3.5A		38	60	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -3A		47	90	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -2A		61	100	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V			-1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -3.5A		9.5		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1.6A	-0.5	-0.75	-1.2	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = -4V, V <sub>GS</sub> = 0V, f = 1MHz		1060		pF
Output Capacitance	C <sub>OSS</sub>			273		
Reverse Transfer Capacitance	C <sub>RSS</sub>			252		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>DD</sub> = -6V, V <sub>GEN</sub> = -4.5V,		13	25	ns
Turn-off Delay Time	T <sub>D(OFF)</sub>	R <sub>L</sub> =6Ω, R <sub>G</sub> = 6Ω, I <sub>D</sub> =-1A		42	70	



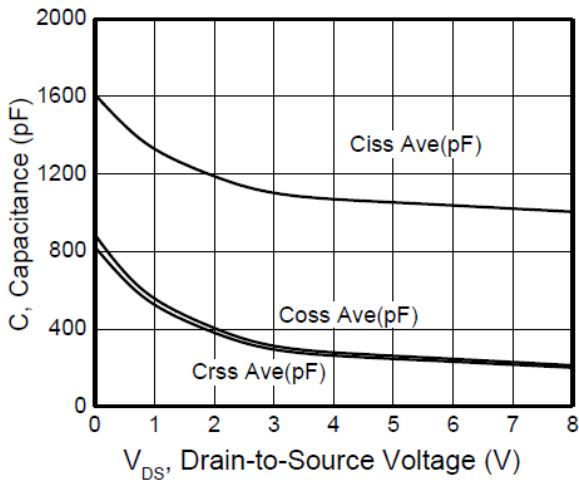
➤ **Typical Performance Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**



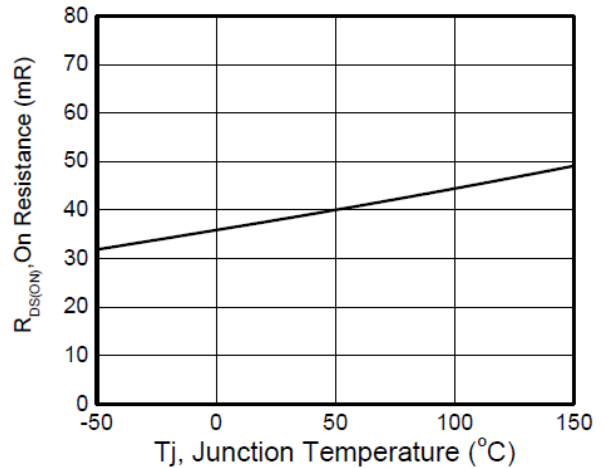
**Figure 1. Output Characteristics**



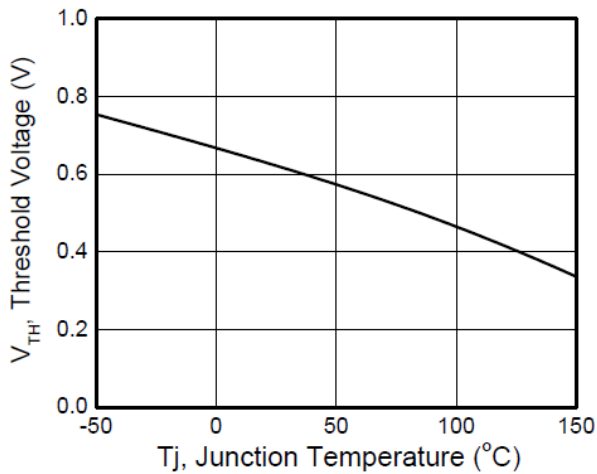
**Figure 2. Transfer Characteristics**



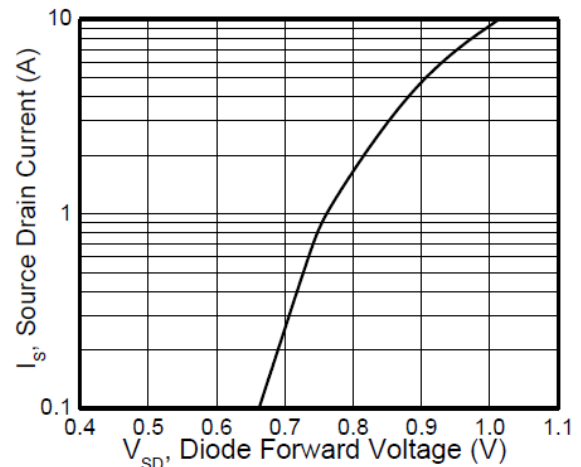
**Figure 3. Capacitance**



**Figure 4. On Resistance vs. Temperature**

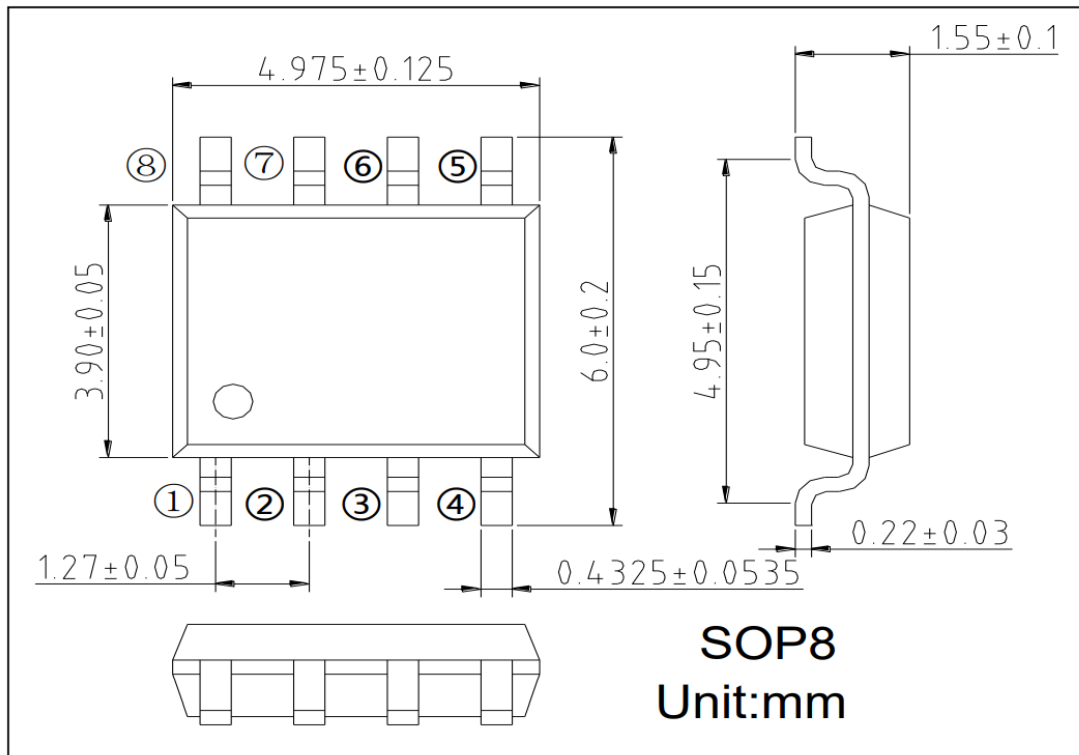


**Figure 5. Gate Threshold vs. Temperature**



**Figure 6. Diode Forward Characteristics**

## ➤ Package Information



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